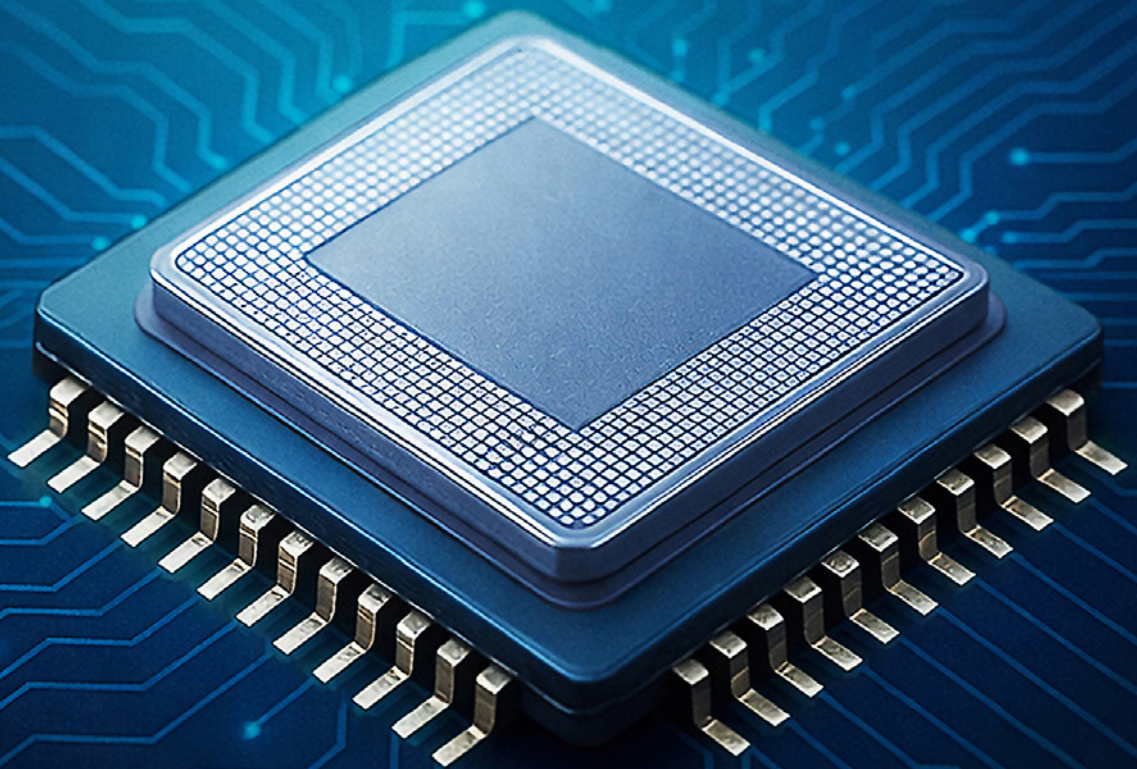


# Semiconductor Catalysts

Advanced Catalysts for Semiconductor Green Process



## PFC Abatement Catalyst

### Product Overview

Product Name	PFC (Perfluorinated Compound) Abatement Catalyst
Application	Catalytic decomposition of PFCs—high GWP gases generated in semiconductor manufacturing
Key Reactions	$\geq 650^{\circ}\text{C}$
Operating Temp.	$\text{CF}_4$ , $\text{C}_2\text{F}_6$ , $\text{SF}_6$ , $\text{CHF}_3$ , and other PFCs



### Product Specifications

Item	Tablet Type	Honeycomb Type
Dimensions	15.2×15.2×10mm	150×150×150mm
Bulk Density	0.66kg/L	1.00kg/L
Destruction Efficiency (DRE)	$\geq 95\%$	$\geq 95\%$
Pressure Drop ( $\Delta P$ )	100% (baseline)	83% (-17%)
Product Code	HE-1540	HE-1530

### Key Features



#### Advanced Catalyst Design

Optimized composition of precious and base metals for process-specific gas treatment (CVD/Etching)



#### Superior Durability

Excellent resistance to fluorine and acid with stable performance  
Over 1 year operational lifetime



#### High Abatement Performance

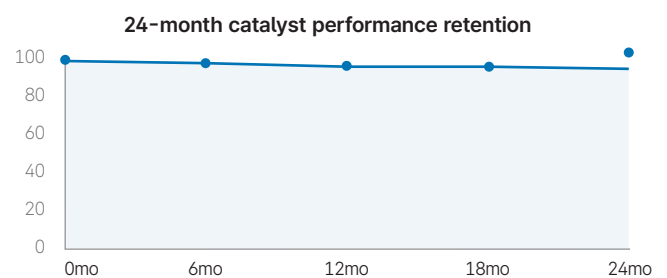
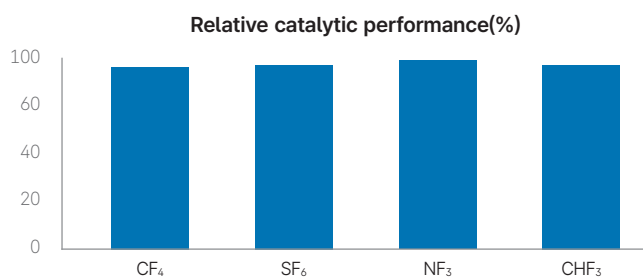
Achieves over 95% DRE  
Efficient decomposition of various PFC gases



#### Customized Solutions

Applicable to semiconductor and LCD manufacturing processes  
Compatible with POU and scrubber

### Performance Data



### Applications



#### Semiconductor Manufacturing

PFC abatement in CVD and etching processes



#### Display Manufacturing

PFC abatement for display fabrication processes



#### POU & Centralized Scrubber

Applicable to both POU equipment and centralized scrubber systems

Supporting Greenhouse Gas Reduction and ESG Goals through PFC Abatement

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## POU N<sub>2</sub>O Decomposition Catalyst

### Product Overview

Product Name	POU (Point-of-Use) N <sub>2</sub> O Decomposition Catalyst
Application	Catalytic decomposition of nitrous oxide (N <sub>2</sub> O), a greenhouse gas generated in semiconductor CVD and etching processes, into environmentally benign gases
Reaction	$N_2O \rightarrow N_2 + \frac{1}{2}O_2$
Operating Temperature	≥ 550°C
Destruction Efficiency	≥ 95%



### Product Specifications

N <sub>2</sub> O Decomposition Catalyst	
Type / Size (mm)	Honeycomb / 150 × 150 × H (50–150)
Bulk Density	1.00 kg/L
Operating Temp.	550°C (Typical range: 550–650°C)
Durability	≥ 6 months (depending on process conditions)

### Key Features



#### Cost-Effective Operation

Up to 40% reduction in operating costs compared to plasma systems



#### Excellent Durability

Stable long-term performance  
Reduced maintenance cost



#### High N<sub>2</sub>O Decomp. Efficiency

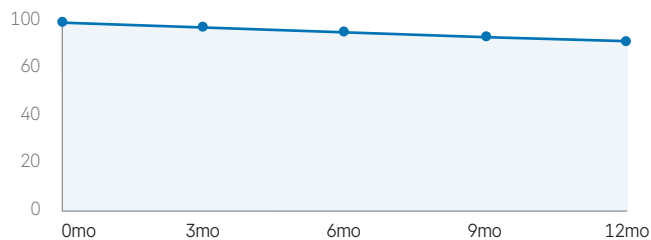
Over 95% abatement efficiency  
Meeting greenhouse gas regulation to plasma systems



#### Low Pressure Drop

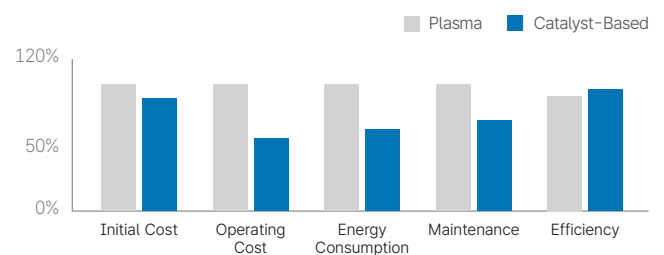
Honeycomb structure minimizes pressure loss

### Performance Data



≥95% DRE within the design temperature window (≥550°C)

### Plasma vs. Catalyst Comparison



Up to 40% lower operating cost compared to plasma systems

### Applications



#### Semiconductor Memory Fabs

≥95% N<sub>2</sub>O abatement



#### Display Manufacturing

LCD production processes



#### POU & Centralized Scrubber

Integrated POU modules

Contributing to Greenhouse Gas Reduction and ESG Goals

## NH<sub>3</sub> & IPA Oxidation Catalyst

### Product Overview

Product Name	NH <sub>3</sub> Oxidation (AOC) & IPA Oxidation Catalyst
Application	Removal of residual NH <sub>3</sub> (ammonia) and IPA (isopropyl alcohol) remaining after wet scrubber treatment in semiconductor processes
Operating Temperature	200–450°C
Conversion Efficiency	NH <sub>3</sub> ≥ 95%, IPA ≥ 90%
Technology	Precious metal-based active phase, optimized for secondary abatement systems



Process



Scrubber



NH<sub>3</sub> / IPA Catalyst



Cleaned Exhaust

### Product Specifications

Specifications	
Substrate	Cordierite honeycomb (100–300 CPSI), metallic substrate optional
CPSI Options	100 CPSI (60×60 cells), 200 CPSI (79×79 cells), 300 CPSI (100×100 cells)
Standard Dimensions	150 × 150 × T (50–100) mm
Operating Conditions	GHSV: 10,000–50,000 hr <sup>-1</sup> , moisture tolerance: 5–20% H <sub>2</sub> O

### Key Features



#### Selective NH<sub>3</sub> Oxidation

High N<sub>2</sub> selectivity with minimized by-product formation  
 ≥95% NH<sub>3</sub> conversion efficiency  
 Optimized design to minimize secondary pollutants



#### High IPA Oxidation Efficiency

≥90% IPA removal efficiency, Simultaneous treatment of VOCs



#### Low-Temp. Activity & Moisture Resistance

Stable operation at relatively low temperatures (200–450°C)  
 Maintains performance under humid conditions (5–20% H<sub>2</sub>O)



#### Easy Process Integration

Seamless integration with scrubbers and CTO systems

### Applications



#### Semiconductor Process Exhaust

NH<sub>3</sub> / IPA abatement from various fab processes



#### Scrubber-Integrated Systems

Minimized downstream emissions after scrubber



#### Etch / Wet Process Lines

Treatment of exhaust gases from etching and wet processes



#### CTO Systems

Catalytic thermal oxidation systems for exhaust gas treatment

Enabling Clean Manufacturing and ESG through Semiconductor Exhaust Abatement

## Company Overview

Global warming is driven by various greenhouse gases and remains a critical global challenge. Global Warming Potential (GWP) is measured relative to CO<sub>2</sub> (baseline = 1), with PFCs up to 7,000 and N<sub>2</sub>O at approximately 310. In semiconductor and display manufacturing, emissions such as PFCs and N<sub>2</sub>O require effective abatement. Heesung Catalysts contributes to greenhouse gas reduction through advanced catalyst technologies.

## Core Capabilities



### PFC / N<sub>2</sub>O Abatement Performance ≥95%

Guaranteed DRE ≥95%



### ISO 9001 / ISO 14001

International quality certification



### Enhanced Poisoning Resistance

Extended catalyst lifetime and stable operation



### Energy-Efficient Design

Reduced power consumption and lower operating costs

## Resource Circularity Services



Fresh Catalyst



Spent Catalyst



Precious Metal Recovery



Regenerated Catalyst

## Customer Services



01  
End-of-Life Catalyst Replacement



02  
Customized Catalyst Design



03  
POU & Large-Scale Stack Configurations



04  
Catalyst Analysis & Evaluation



05  
Process & Equipment Consulting



06  
T/S & A/S

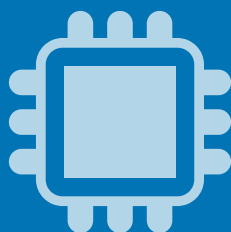
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